

# Thin Film Top-Contact Resistor



Product may not be to scale

The SFM series single-value resistor chips offer a small size, wide ohmic value range and excellent power capacity. The SFMs tantalum nitride resistor material offers excellent resistance to high moisture environments.

The SFMs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The SFMs are 100 % electrically tested and visually inspected to MIL-STD-883.

#### **FEATURES**

· Wire bondable

• Small size: 0.020 inches square • Resistance range: 1.0  $\Omega$  to 1 M $\Omega$ 

• DC power rating: 250 mW

• Oxidized silicon substrate for good power dissipation

· Resistor material tantalum nitride, self passivating

• Moisture resistant

### **APPLICATIONS**

Vishay EFI SFM top-contact resistor chips are designed to handle substantial power loads in many types of hybrid packages. They are ideally suited for this purpose because of their small size.

## TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES AND TOLERANCES Tightest Standard Tolerance Available 0.1 % ± 25 ppm/°C ± 50 ppm/°C ± 100 ppm/°C ± 250 ppm/°C 200 k $\Omega$ 360 k $\Omega$ 620 k $\Omega$ 1 M $\Omega$ 1 $\Omega$ 10 $\Omega$ 30 $\Omega$ 100 $\Omega$

PROCESS CODE				
CLASS H*	CLASS K*			
050	123			
051	122			
045	121			
040	120			

\*MIL-PRF-38534 inspection criteria

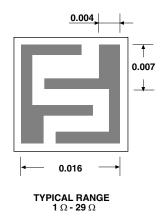
STANDARD ELECTRICAL SPECIFICATIONS			
PARAMETER			
Noise, MIL-STD-202, Method 308 100 $\Omega$ - 250 k $\Omega$ < 100 $\Omega$ or > 251 k $\Omega$	- 35 dB typ. - 20 dB typ.		
Moisture Resistance, MIL-STD-202 Method 106	± 0.5 % max. Δ <i>R/R</i>		
Stability, 1000 h, + 125 °C, 125 mW	± 0.25 % max. Δ <i>R/R</i>		
Operating Temperature Range	- 55 °C to + 125 °C		
Thermal Shock, MIL-STD-202, Method 107, Test Condition F	± 0.25 % max. Δ <i>R</i> / <i>R</i>		
High Temperature Exposure, + 150 °C, 100 h	$\pm$ 0.5 % max. $\Delta R/R$		
Dielectric Voltage Breakdown	200 V		
Insulation Resistance	10 <sup>12</sup> min.		
Operating Voltage	100 V max.		
DC Power Rating at + 70 °C (Derated to Zero at + 175 °C)	250 mW		
5 x Rated Power Short-Time Overload, + 25 °C, 5 s	± 0.25 % max. Δ <i>R/R</i>		

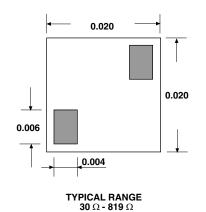
For technical questions, contact: efi@vishav.com Document Number: 61017 Revision: 12-Mar-08

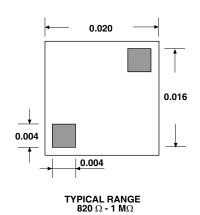


## Thin Film Top-Contact Resistor

### **CONFIGURATIONS** in inches







Vishay Electro-Films

**SCHEMATIC** 



MECHANICAL SPECIFICATIONS in inches			
PARAMETER			
Chip Size	$0.020 \times 0.020 \pm 0.003 (0.5 \times 0.5 \pm 0.076 \text{ mm})$		
Chip Thickness	0.010 ± 0.002 (0.254 ± 0.05 mm)		
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO <sub>2</sub>		
Resistor Material	Tantalum nitride, self-passivating		
Bonding Pad Size	0.004 x 0.004 (0.10 x 0.10 mm)		
Number of Pads	2		
Pad Material	25 kÅ minimum aluminum		
Backing	None, lapped semiconductor silicon		

Gold backing for eutectic die attach

Gold bonding pads, 15 kÅ minimum thickness

Consult Applications Engineer

ORDERING INFORMATION								
Example: 100 % visual, 10 kΩ, ± 1 %, ± 100 ppm/°C TCR, aluminum pads, class H visual inspection								
<b>W</b> INSPECTION/ PACKAGING	SFM PRODUCT FAMILY	<b>045</b> PROCESS CODE	<b>1000</b> RESISTANCE VALUE	1 MULTIPLIER CODE	<b>F</b> TOLERANCE CODE			
W = 100 % visually inspected parts in matrix tray per MIL-STD-883		See Process Code table	Use first 4 digits of resistance	<b>C</b> = 0.001 <b>B</b> = 0.01	<b>B</b> = 0.1 % <b>C</b> = 0.2 % <b>D</b> = 0.5 %			
X = Sample , commercial visually inspected parts loaded in matrix trays (4 % AQL)		<b>A</b> = 0.1 <b>0</b> = 1 <b>1</b> = 10	<b>F</b> = 1.0 % <b>G</b> = 2.0 % <b>H</b> = 2.5 %					
				<b>2</b> = 100 <b>3</b> = 1000 <b>4</b> = 10 000	J = 5.0 % K = 10 % *Coating standa			

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Vishay

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